



PRODUCT BULLETIN # 20671

Generic Copy

Issue Date: 23-Oct-2014

TITLE: NCL30082BDR2G, NCL30082B1DR2G conversions from MSL1 to MSL3

PROPOSED FIRST SHIP DATE: 23-Oct-2014

AFFECTED CHANGE CATEGORY(S): Assembly Process Moisture Sensitivity Level (MSL)

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor sales office or <Scott.Brow@onsemi.com>

NOTIFICATION TYPE:

ON Semiconductor considers this change approved unless specific conditions of acceptance are provided in writing. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

ON Semiconductor would like to announce that it will be changing the Moisture Sensitivity Level for those products listed in this Product Bulletin from MSL1 to MSL3. This means that the product listed in this product bulletin will be shipped in dry packing materials. There has been no change in the BOM materials.

List of affected General Parts:

NCL30082BDR2G
NCL30082B1DR2G